

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Metal oxide	Lead Dioxide (PbO2)	1309-60-0	0.00162	0.66	0.09702
	Doped silicon	Silicon (Si)	7440-21-3	0.24392	99.34	14.60298
Subtotal				0.24554	100	14.7
Post-plating	Lead alloy	Tin (Sn)	7440-31-5	0.45433	100.0	27.2
		Subtotal				0.45433
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02005	0.03	1.20057
	Copper alloy	Iron (Fe)	7439-89-6	0.06684	0.1	4.0019
	Copper alloy	Copper (Cu)	7440-50-8	66.7576	99.87	3,996.69753
Subtotal				66.84449	100	NaN
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.0939	6.5	125.359
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	5.1542	16.0	308.576
	Filler	Silica fused	60676-86-0	22.87178	71.0	1,369.306
	Flame retardant	Metal hydroxide		2.0939	6.5	125.359
Subtotal				32.21378	100	NaN
Solder Wire	Lead alloy	Tin (Sn)	7440-31-5	0.00458	5.0	0.274
		Silver (Ag)	7440-22-4	0.00229	2.5	0.137
		Lead (Pb)	7439-92-1	0.08467	92.5	5.069
Subtotal				0.09154	100	5.48
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.15033	100.0	9
				Subtotal		
Total				100.00001	100	NaN

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.